

Description

This 60V,100A N-Channel MOSFET in a TO-263 Plastic Package.

Applications

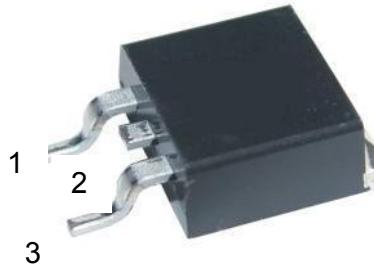
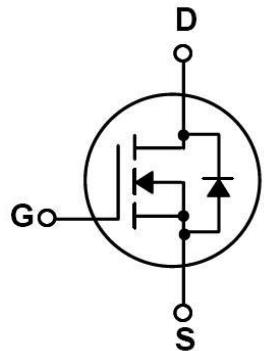
These devices are well suited for high efficiency switching DC/DC converters and switch mode power supplies

Features

- Low gate charge
- Low crss
- Fast Switching
- Halogen-free Product

V_{DSS}	$R_{DS(on)}(\text{Typ})$	I_D
60V	5.9mΩ	100A

Equivalent Circuit & Pinning



Pin1:Gate

Pin2:Drain

Pin3:Source

Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DSS}	60	V
Drain Current	I _D (T _c =25°C)	100	A
Peak Drain Current	I _{DM}	380	A
Gate-Source Voltage	V _{GSS}	±20	V
Single Pulsed Avalanche Energy	E _{AS}	602	mJ
Avalanche Current	I _{AS}	38.9	A
Total Power Dissipation	P _D (T _c =25°C)	188	W
Junction and Storage Temperature Range	T _J , T _{STG}	-55 to 150	°C
Thermal Resistance-Junction to Case	R _{θJC}	0.8	°C/W
Thermal Resistance-Junction to Ambient	R _{θJA}	62.5	

Electrical Characteristics(Ta=25°C)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	60			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V V _{GS} =0V			1	μA
		V _{DS} =60V V _{GS} =0V T _J =125°C			10	μA
Gate-Body leakage current	I _{GSS}	V _{GS} =±20V V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} I _D =250μA	2	2.6	4	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =10V I _D =50A		5.9	7	mΩ

Electrical Characteristics($T_a=25^\circ C$)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Diode Forward Voltage	V_{SD}	$I_S=1A \quad V_{GS}=0V$ $V_{GS}=0V \quad V_{DS}=25V, f=1.0MHz$		0.6	1.2	V
Input Capacitance	C_{iss}			4920		pF
Output Capacitance	C_{oss}			295		
Reverse Transfer Capacitance	C_{rss}			133		
Gate resistance	R_g	$V_{GS}=0V \quad V_{DS}=0V, f=1MHz$ $V_{GS}=10V \quad V_{DS}=30V \quad I_D=50A$		1.2		Ω
Total Gate Charge	$Q_g(10V)$			53	75	nC
Total Gate Charge	$Q_g(4.5V)$			22	31	
Gate Source Charge	Q_{gs}			17		
Gate Drain Charge	Q_{gd}			5		ns
Turn-On DelayTime	$t_{D(on)}$	$V_{DD}=30V \quad I_D=50A$ $V_{GS}=10V \quad R_G=2.5\Omega$		18		
Turn-On Rise Time	t_r			20		
Turn-Off DelayTime	$t_{D(off)}$			33		
Turn-Off Fall Time	t_f			4		

A. The value of R_{qJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ C$. The Power dissipation PDSM is based on R_{qJA} and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design, and the maximum temperature of 150°C may be used if the PCB allows it.

B. The power dissipation PD is based on $T_{J(MAX)}=150^\circ C$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^\circ C$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ C$.

D. The R_{qJA} is the sum of the thermal impedance from junction to case R_{qJC} and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300ms pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}=150^\circ C$. The SOA curve provides a single pulse rating.

G. The maximum current limited by package.

H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ C$.

Electrical Characteristic Curve

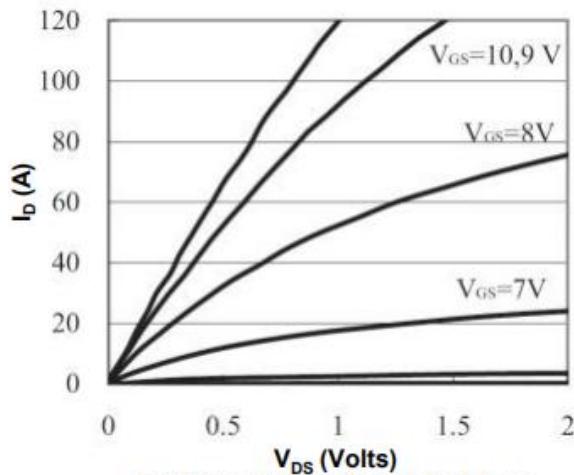


Fig 1: On-Region Characteristics

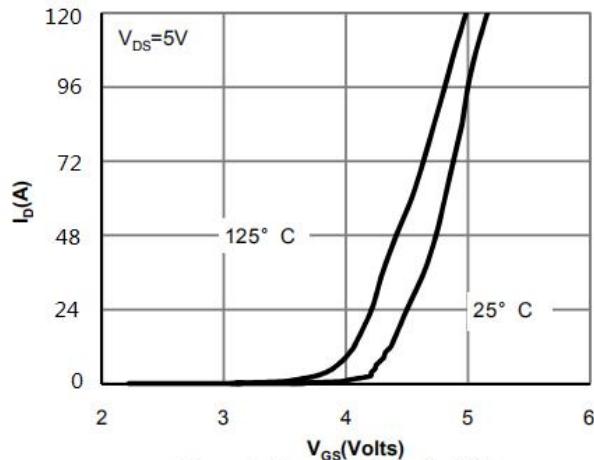


Figure 2: Transfer Characteristics

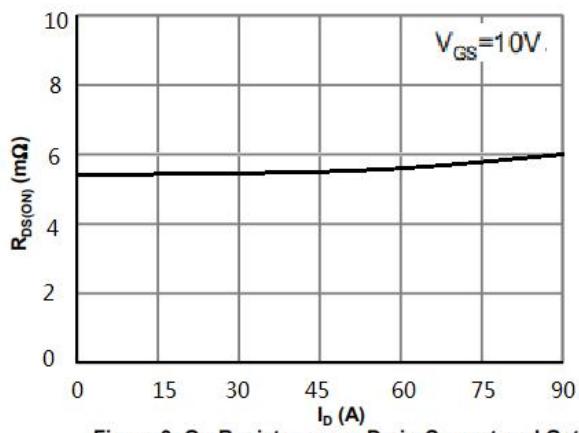


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

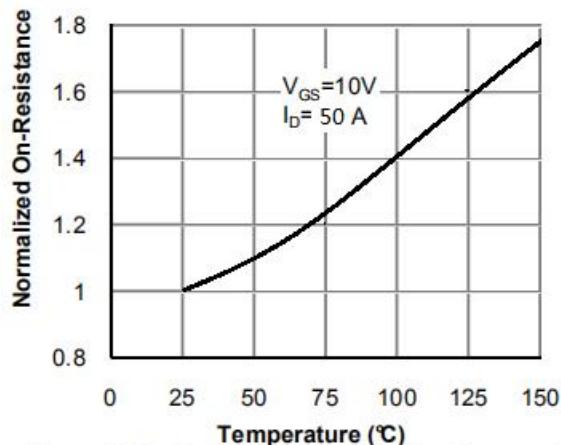


Figure 4: On-Resistance vs. Junction Temperature

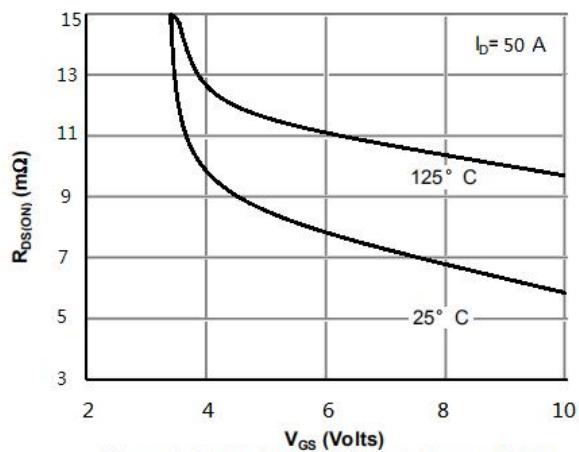


Figure 5: On-Resistance vs. Gate-Source Voltage

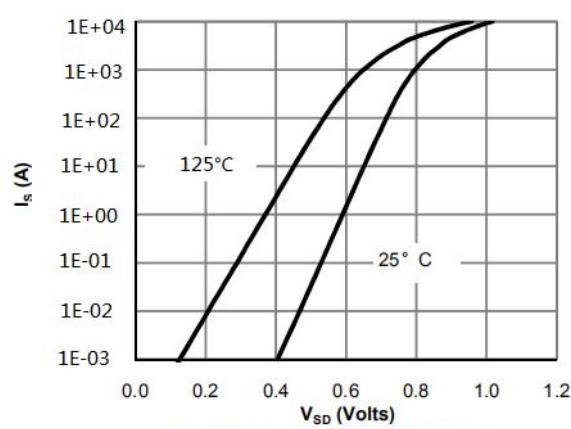


Figure 6: Body-Diode Characteristics

Electrical Characteristic Curve

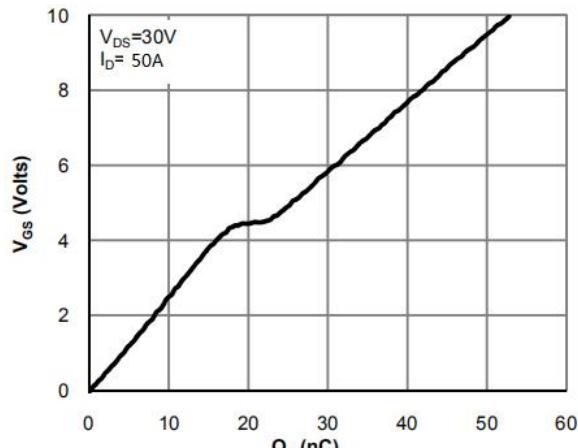


Figure 7: Gate-Charge Characteristics

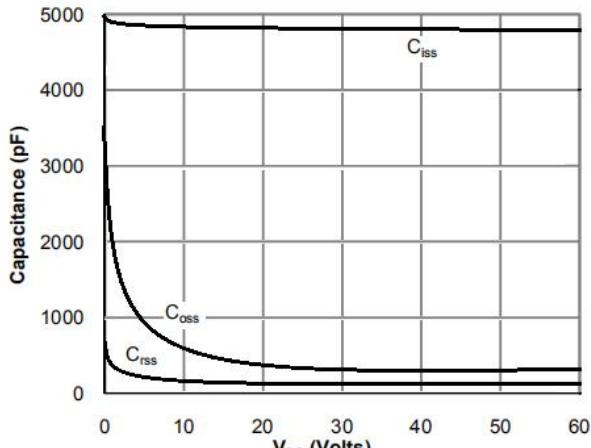


Figure 8: Capacitance Characteristics

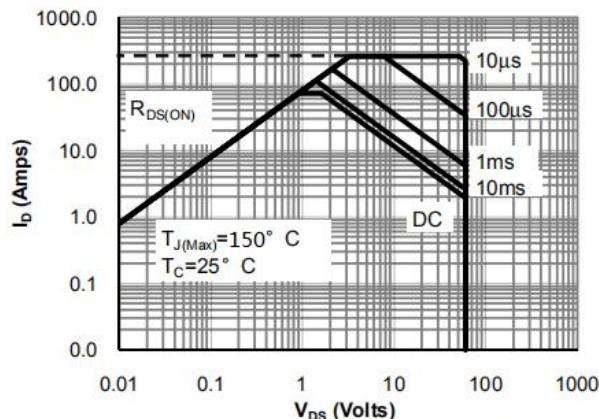


Figure 9: Maximum Forward Biased Safe Operating Area

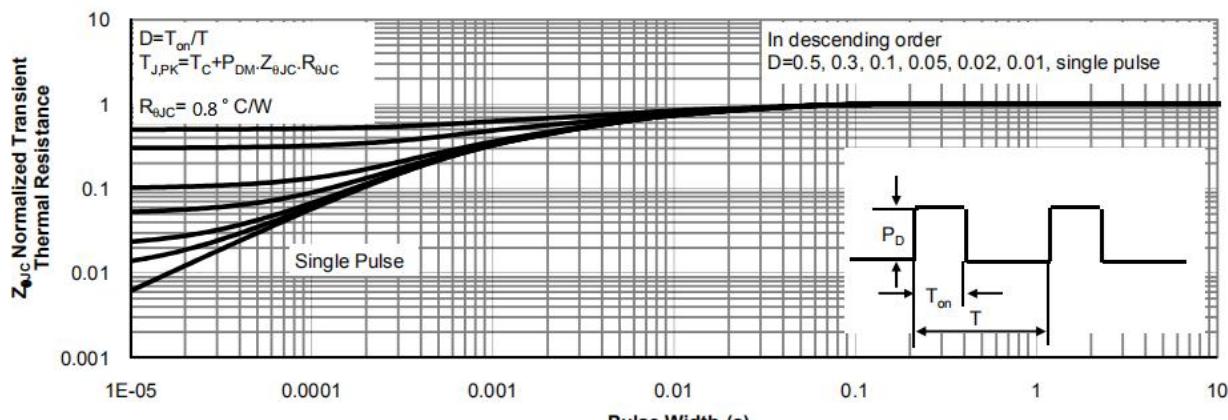
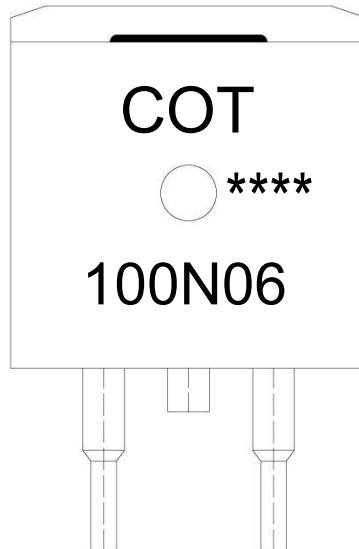


Figure 10 : Normalized Maximum Transient Thermal Impedance

Marking Instructions



Note:

COT: Company Logo

100N06: Product Type.

****: Lot No. Code, code change with Lot No.

Packaging SPEC.

REEL INFORMATION

Package Type	Units					Dimension (unit: mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
TO-263	800	1	800	5	4,000	13" ×24	360×360×50	385×257×392

TUBE INFORMATION

Package Type	Units					Dimension (unit: mm ³)		
	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Tube	Inner Box	Outer Box
TO-263	50	20	1,000	5	5,000	532×33×7.0	555×164×50	575×290×180

Package Outline Dimensions

